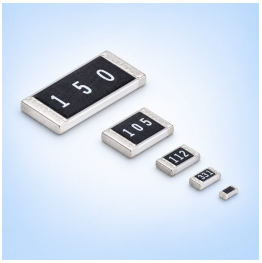
RM / RMK / RMS / RMZ / RMHT / RMHV / RMKH

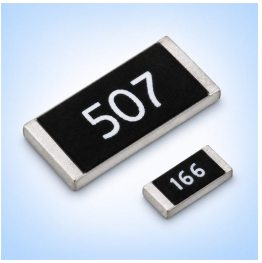
Integrated Chip Resistor Selection Datasheet

Electrical selection, packages, tolerances, derating and qualification for 19 product families. Reference numbers identify the source family and distinguish identical model names with different technologies or grades.









Family index and selection coverage

Ref.	Family / technology	Power W	Series resistance coverage
01	RM power thick film	0.25–6	1 Ω–22 MΩ
02	RM anti-sulfur thick film	0.05–3	1 Ω–22 MΩ
03	RM anti-sulfur zero-ohm	0.05–1	0 Ω; ≤50 mΩ
04	RM standard thick film	0.05–3	1 Ω–22 MΩ
05	RM thin film	0.031–0.5	1 Ω–3 MΩ
06	RMHT high-temperature thick film	0.05–1	1 Ω–22 MΩ
07	RMK GJB thick film	0.05–1	1 Ω–22 MΩ
08	RMK GJB thin film	0.05–1	10 Ω–4.9 MΩ
09	RMS pulse / surge	1 / 2	0.4 Ω–30 Ω
10	RM sulfur-resistant thick film	0.05–3	1 Ω–22 MΩ
11	RM1608 gold-electrode chip	0.09 / 0.5	1 Ω–1 MΩ
12	RMK space-grade YC thick film	0.05–1	0.1 Ω–22 MΩ
13	RMK YG-grade thick film	0.05–1	10 Ω–1 MΩ
14	RMK GJB sulfur-resistant thick film	0.05–1	1 Ω–22 MΩ
15	RMKH precision / reliability	0.032–1	10 Ω–1 MΩ
16	RMS automotive surge	0.1–2	1 Ω–10 MΩ
17	RMZ GJB sulfur-resistant zero-ohm	0.05–1	0 Ω; ≤20 / 25 / 30 mΩ
18	RMZ space-grade YC zero-ohm	0.05–1	0 Ω; ≤20 / 25 / 30 mΩ
19	RMHV high voltage	0.1–1	100 kΩ–500 MΩ

Coverage is an index only. Select tolerance, TCR, limiting voltage, rating conditions and package from the detailed model tables and the applicable reference.

01 / SERIES TECHNICAL DATA

Electrical ratings and resistance bands

P is rated power and Umax is limiting element voltage. TCR in ppm/K equals 10^-6/K. Apply the corresponding derating curve. Ratings remain family-specific even when package names are identical.

02, 04, 10 RM standard thick film

Model	P / W	Umax / V	Resistance range	Tolerance ±%	TCR / ppm/K
RM1005	0.05	30	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RM1608	0.1	50	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RM2012	0.15	50	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RM3216	0.25	100	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RM3225	0.5	150	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RM5025	0.8	150	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RM6332	1	150	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RM4225	1	200	1 Ω–10 MΩ	±1 / ±2 / ±5	±100 / ±300
RM6308	2	200	1 Ω–10 MΩ	±1 / ±2 / ±5	±100 / ±300
RM3263	3	200	8.2 Ω–1 MΩ	±1 / ±2 / ±5	±100 / ±300

Common ratings for 02 anti-sulfur, 04 standard and 10 sulfur-resistant thick film. Family 02 specifies ±300 ppm/K only for 1 Ω≤R<10 Ω. Other cases follow the listed K/M options. Operating ranges are -65 to +150 °C for 02 and -55 to +125 °C for 04/10. Ordering suffixes are listed later.

01 RM power thick film

Model	Power W	Resistance	Tolerance %	Limit V	TCR ppm/K
RM1608-0.25W	0.25	1 Ω≤R≤22 MΩ	±1, ±2, ±5	50	1 Ω≤R<10 Ω: ±300; 10 Ω≤R≤22 MΩ: ±100, ±300
RM2012-0.5W	0.5	1 Ω≤R≤22 MΩ	±1, ±2, ±5	50	1 Ω≤R<10 Ω: ±300; 10 Ω≤R≤22 MΩ: ±100, ±300
RM3216-1W	1	1 Ω≤R≤22 MΩ	±1, ±2, ±5	100	1 Ω≤R<10 Ω: ±300; 10 Ω≤R≤22 MΩ: ±100, ±300
RM3225-1WA	1	1 Ω≤R≤22 MΩ	±1, ±2, ±5	150	1 Ω≤R<10 Ω: ±300; 10 Ω≤R≤22 MΩ: ±100, ±300
RM5025-2W	2	1 Ω≤R≤22 MΩ	±1, ±2, ±5	150	1 Ω≤R<10 Ω: ±300; 10 Ω≤R≤22 MΩ: ±100, ±300
RM6332-5W	5	10 Ω≤R<100 Ω	±1, ±2, ±5	200	±300
RM6332-5W	5	3 kΩ<R≤6 kΩ	±1, ±2, ±5	200	±300

Model	Power W	Resistance	Tolerance %	Limit V	TCR ppm/K
RM6332-5W	5	100 Ω≤R≤3 kΩ	±1, ±2, ±5	200	±100, ±300
RM6363-4W	4	10 Ω≤R≤1000 Ω	±10	63.3	±300
RM6363-6W	6	10 Ω≤R≤1000 Ω	±5	77.5	±300

Operating range -55 to +125 °C. Select RM6332 TCR by resistance band. The source exempts RM6363 from its sulfur-test requirement.

06 RMHT high-temperature thick film

Model	P / W	Umax / V	Resistance range	Tolerance ±%	TCR / ppm/K
RMHT1005	0.05	30	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RMHT1608	0.1	50	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RMHT2012	0.15	50	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RMHT3216	0.25	100	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RMHT3225	0.5	150	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RMHT5025	0.8	150	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300
RMHT6332	1	200	1 Ω–22 MΩ	±1 / ±2 / ±5	±100 / ±300

Operating range -55 to +200 °C. See the thermal and qualification sections for the derating knee and life-test temperature.

07, 12, 13, 14 RMK GJB thick film

Model	P / W	Umax / V	Resistance range	Tolerance ±%	TCR / ppm/K
RMK1005	0.05	30	See family conditions	See family conditions	±100 / ±300
RMK1608	0.1	50	See family conditions	See family conditions	±100 / ±300
RMK2012	0.15	50	See family conditions	See family conditions	±100 / ±300
RMK3216	0.25	100	See family conditions	See family conditions	±100 / ±300
RMK3225	0.5	150	See family conditions	See family conditions	±100 / ±300
RMK5025/5225	0.8	150	See family conditions	See family conditions	±100 / ±300
RMK6332	1	200	See family conditions	See family conditions	±100 / ±300

Ref.	Resistance	Tolerance ±%	Rating exception
07 / 14	1 Ω–22 MΩ	1 / 2 / 5	—
12	1005: 1 Ω–22 MΩ; others: 0.1 Ω–22 MΩ	0.5 / 1 / 2 / 5	RMK1005 Umax is 25 V
13	10 Ω–1 MΩ	1 / 2 / 5	—

Operating range -65 to +150 °C for 07, 12, 13 and 14. RMK5025/5225 is retained as named in the applicable source. Specify both model and grade.

05 RM thin film

Model	Power W	Limit V	Resistance Ω	Tolerance ±%	TCR ppm/K
RM1005	0.031	30	49.9≤R≤12k	0.05, 0.1	±10
RM1005	0.031	30	10≤R≤255k	0.1, 0.25, 0.5, 1	±25, ±50
RM1005	0.031	30	1≤R≤10	0.5, 1	±50
RM1608	0.063	50	4.7≤R≤332k	0.05, 0.1	±10
RM1608	0.063	50	4.7≤R≤1M	0.1, 0.25, 0.5, 1	±25, ±50
RM1608	0.063	50	2≤R≤4.7	0.25, 0.5, 1	±25, ±50
RM1608	0.063	50	1≤R≤2	0.25, 0.5, 1	±50
RM2012	0.1	50	4.7≤R≤511k	0.05, 0.1	±10
RM2012	0.1	50	4.7≤R≤2M	0.1, 0.25, 0.5, 1	±25, ±50
RM2012	0.1	50	1≤R≤4.7	0.25, 0.5, 1	±25, ±50
RM3216	0.125	100	4.7≤R≤1M	0.05	±10
RM3216	0.125	100	4.7≤R≤2.49M	0.1, 0.25, 0.5, 1	±25, ±50
RM3216	0.125	100	1≤R≤4.7	0.25, 0.5, 1	±25, ±50
RM3225	0.25	150	4.7≤R≤1M	0.05	±10
RM3225	0.25	150	4.7≤R≤2.49M	0.1, 0.25, 0.5, 1	±25, ±50
RM3225	0.25	150	1≤R≤4.7	0.25, 0.5, 1	±25, ±50
RM5025	0.4	150	4.7≤R≤1M	0.05, 0.1	±10
RM5025	0.4	150	4.7≤R≤1M	0.1, 0.25, 0.5, 1	±25, ±50
RM6332	0.5	200	4.7≤R≤1M	0.05, 0.1	±10
RM6332	0.5	200	4.7≤R≤3M	0.1, 0.25, 0.5, 1	±25, ±50
RM6332	0.5	200	1≤R≤4.7	0.25, 0.5, 1	±25, ±50

08 RMK GJB thin film

Model	Power W	Limit V	Resistance Ω	Tolerance ±%	TCR ppm/K
RMK1005	0.05	30	50≤R≤50k	0.05	±25, ±50
RMK1005	0.05	30	25≤R≤1M	0.1, 0.25, 0.5	±25, ±50
RMK1608	0.1	50	50≤R≤260k	0.05	±25, ±50
RMK1608	0.1	50	10≤R≤301k	0.1	±25, ±50
RMK1608	0.1	50	10≤R≤499k	0.25, 0.5	±25, ±50

Model	Power W	Limit V	Resistance Ω	Tolerance ±%	TCR ppm/K
RMK2012	0.15	50	50≤R≤300k	0.05	±25, ±50
RMK2012	0.15	50	10≤R≤510k	0.1, 0.25, 0.5	±25, ±50
RMK3216	0.25	100	50≤R≤499k	0.05	±25, ±50
RMK3216	0.25	100	10≤R≤1M	0.1, 0.25, 0.5	±25, ±50
RMK3225	0.5	150	50≤R≤499k	0.05	±25, ±50
RMK3225	0.5	150	10≤R≤1M	0.1, 0.25, 0.5	±25, ±50
RMK5025	0.8	150	50≤R≤499k	0.05	±25, ±50
RMK5025	0.8	150	10≤R≤4.9M	0.1, 0.25, 0.5	±25, ±50
RMK6332	1	200	50≤R≤499k	0.05	±25, ±50
RMK6332	1	200	10≤R≤4.9M	0.1, 0.25, 0.5	±25, ±50

15 RMKH precision / reliability

Model	P / W	Umax / V	Resistance range	Tolerance ±%	TCR / ppm/K
RMKH1005	0.032	25	10 Ω–1 MΩ	±0.1 / ±0.25 / ±0.5	±100 / ±300
RMKH1608	0.063	40	10 Ω–1 MΩ	±0.1 / ±0.25 / ±0.5	±100 / ±300
RMKH2012	0.1	50	10 Ω–1 MΩ	±0.1 / ±0.25 / ±0.5	±100 / ±300
RMKH3216	0.25	100	10 Ω–1 MΩ	±0.1 / ±0.25 / ±0.5	±100 / ±300
RMKH3225	0.5	150	10 Ω–1 MΩ	±0.1 / ±0.25 / ±0.5	±100 / ±300
RMKH5025	0.8	150	10 Ω–1 MΩ	±0.1 / ±0.25 / ±0.5	±100 / ±300
RMKH6332	1	150	10 Ω–1 MΩ	±0.1 / ±0.25 / ±0.5	±100 / ±300

11 RM1608 gold-electrode chip

Model	Power W	Resistance	Tolerance %	Limit V	TCR ppm/K
RM1608	0.09	10 Ω≤R<100 Ω	±5	90	±300
RM1608	0.09	100 Ω≤R≤1 MΩ	±1, ±2, ±5	90	±100, ±300
RM1608	0.5	1 Ω≤R≤1 MΩ	±5	90	±300

Maximum mounting-surface temperature is 70 °C at 0.09 W and 100 °C at 0.5 W. The gold-electrode type uses single-sided wire-bond terminations.

16 RMS automotive surge

Model	P / W	Umax / V	Max. overload voltage / V
RMS1005	0.1	50	100
RMS1608	0.2	100	200
RMS2012	0.25 / 0.5	200	400
RMS3216	0.5	200	400
RMS3225	0.5	200	500
RMS5025	1	200	500
RMS6332	2	200	500

Resistance 1 Ω–10 MΩ; tolerances ±1%, ±2%, ±5%. The source lists ±250 ppm/°C for 1–10 Ω and ±100/±250 ppm/°C for 10 Ω–10 MΩ. Confirm the 10 Ω boundary and the RMS2012 0.25/0.5 W configuration when ordering.

19 RMHV high voltage

Model	P / W	Umax / V	Resistance range
RMHV1608	0.1	300	100 kΩ~100 MΩ
RMHV2012	0.15	400	100 kΩ~100 MΩ
RMHV3216	0.25	2000	100 kΩ~300 MΩ
RMHV3225	0.5	2500	100 kΩ~300 MΩ
RMHV5025	0.8	3000	100 kΩ~500 MΩ
RMHV6332	1	4000	100 kΩ~500 MΩ

The source lists ±2%/±5% and ±300 ppm/K for 100 kΩ–100 MΩ, and ±5%/±10% and ±700 ppm/K for ≥100 MΩ. The 100 MΩ boundary overlaps and requires confirmation. Clean residues and provide insulation after assembly.

09 RMS pulse-load selection

Model	Power W	Pulse W	Pulse time ms	Resistance Ω	TCR ppm/K
RMS6363A	1	400	50	1~30	±300
RMS6363A	1	200	300	1~30	±300
RMS7142A	2	200	200	0.4≤R<1	Not assessed
RMS7142A	2	400	200	1≤R≤10	±300
RMS7142A	2	400	100	10~30	±300
RMS4271A	2	400	200	1~10	±300
RMS4271A	2	25	5000	1~10	±300

Tolerance ±5%. Pulse power and duration are paired conditions. The RMS7142A 10 Ω boundary is retained from the source and requires confirmation.

03 / 17 / 18 Zero-ohm models and current

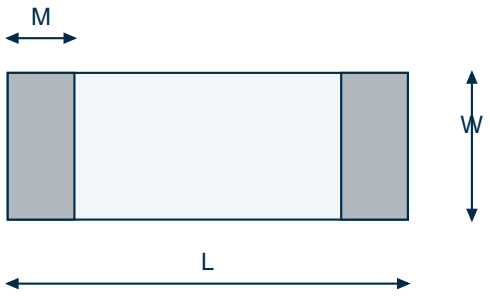
Ref.	Model	P / W	Max. resistance / mΩ	Max. current / A
03	RM0603G	0.05	≤50	1
03	RM1005	0.05	≤50	0.5
03	RM1608	0.1	≤50	1
03	RM2012	0.15	≤50	1
03	RM3216	0.25	≤50	2
03	RM3225	0.5	≤50	2
03	RM5025	0.8	≤50	2
03	RM6332	1	≤50	2

Ref.	Model	P / W	Max. resistance / mΩ	Max. current / A
17, 18	RMZ1005	0.05	30	1.3
17, 18	RMZ1608	0.1	30	1.8
17, 18	RMZ2012	0.15	20	2.7
17, 18	RMZ3216	0.25	25	3.2
17, 18	RMZ3225	0.5	25	4.47
17, 18	RMZ5025	0.8	25	5.7
17, 18	RMZ6332	1	25	6.3

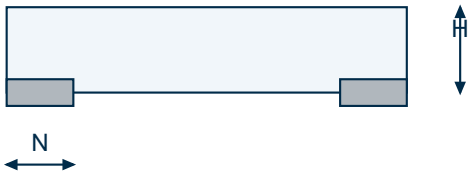
Zero-ohm operating range -65 to +150 °C. Select by both maximum resistance and current. Family 03 is anti-sulfur, 17 is GJB sulfur-resistant and 18 is space-grade YC; qualification and ordering codes are family-specific.

02 / SERIES TECHNICAL DATA

Package dimensions and tolerances



Top view



Side view

All dimensions are in mm. L, W and H are body length, width and height. M and N are termination dimensions as shown in the source drawings. Family 11 lists M only; N is shown as "—".

Ref.	Model	L	W	H	M	N
01	RM1608-0.25W	1.60±0.15	0.80±0.15	0.50±0.15	0.30±0.15	0.30±0.15
01	RM2012-0.5W	2.00±0.20	1.25±0.20	0.55±0.15	0.38±0.20	0.38±0.20
01	RM3216-1W	3.20±0.20	1.60±0.20	0.60±0.20	0.38±0.25	0.38±0.25
01	RM3225-1WA	3.20±0.20	2.50±0.20	0.60±0.20	0.50±0.25	0.50±0.25
01	RM5025-2W	5.00±0.20	2.50±0.20	0.60±0.20	0.60±0.25	0.60±0.25
01	RM6332-5W	6.30±0.20	3.20±0.20	1.10±0.20	0.60±0.25	1.00±0.25
01	RM6363-4W	6.35±0.25	6.35±0.25	1.05±0.25	0.60±0.25	1.00±0.25
01	RM6363-6W	6.35±0.25	6.35±0.25	1.05±0.25	0.60±0.25	1.00±0.25
02, 04, 10	RM1005	1.00±0.15	0.50±0.10	0.35±0.10	0.20±0.15	0.25±0.10
02, 04, 10	RM1608	1.60±0.15	0.80±0.15	0.50±0.15	0.30±0.15	0.30±0.15
02, 10	RM2012	2.00±0.20	1.25±0.20	0.55±0.10	0.38±0.20	0.38±0.20
02, 04, 10	RM3216	3.20±0.20	1.60±0.20	0.60±0.20	0.38±0.25	0.38±0.25
02, 04, 10	RM3225	3.20±0.20	2.50±0.20	0.60±0.20	0.50±0.25	0.50±0.25
02, 04, 10	RM5025	5.00±0.20	2.50±0.20	0.60±0.20	0.60±0.25	0.60±0.25
02, 04, 10	RM6332	6.30±0.20	3.20±0.20	0.60±0.20	0.60±0.25	0.60±0.25
02, 04, 10	RM4225	4.20±0.20	2.50±0.20	1.05±0.20	0.70±0.20	1.20±0.15
02, 04, 10	RM6308	6.30±0.20	3.20±0.20	0.90±0.20	0.60±0.25	0.65±0.25
02, 04, 10	RM3263	3.20±0.15	6.30±0.30	1.05±0.25	0.50±0.25	0.60±0.25
03	RM0603G	0.60±0.03	0.30±0.03	0.23±0.03	0.15±0.05	0.15±0.05
03	RM1005	1.00±0.20	0.50±0.15	0.25~0.84	0.20±0.10	0.25±0.10
03	RM1608	1.60±0.20	0.80±0.15	0.25~0.84	0.30±0.20	0.30±0.15

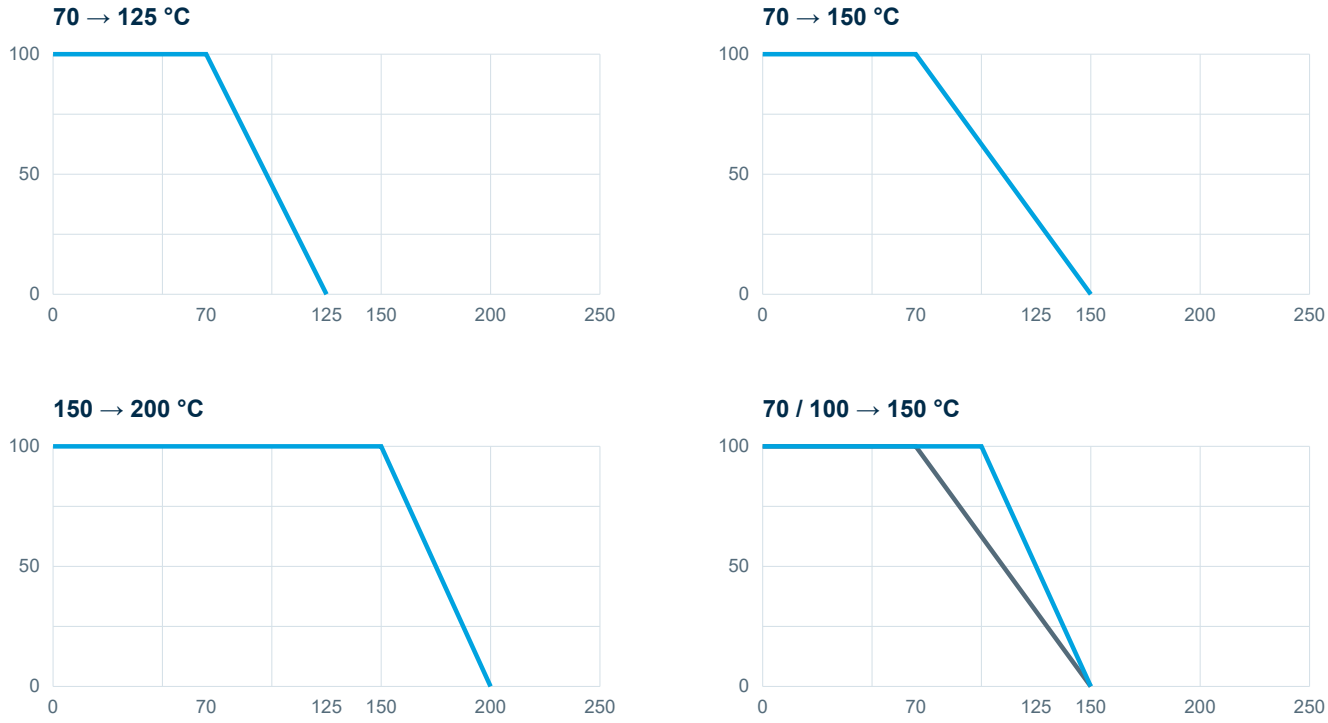
Ref.	Model	L	W	H	M	N
03	RM2012	2.00±0.20	1.25±0.15	0.50±0.25	0.38±0.20	0.38±0.15
03	RM3216	3.20±0.20	1.60±0.15	0.38~0.84	0.38±0.20	0.38±0.15
03	RM3225	3.20±0.15	2.50±0.15	0.38~0.84	0.50±0.25	0.50±0.25
03	RM5025	5.00±0.15	2.50±0.15	0.38~0.84	0.60±0.25	0.60±0.25
03	RM6332	6.30 +0.25/-0.15	3.20±0.15	0.38~0.84	0.60±0.25	0.60±0.25
04	RM2012	2.00±0.20	1.25±0.20	0.55±0.20	0.38±0.20	0.38±0.20
05	RM1005	1.00±0.15	0.50±0.10	0.30±0.15	0.25±0.10	0.25±0.10
05	RM1608	1.60±0.15	0.80±0.15	0.45±0.15	0.30±0.15	0.30±0.15
05	RM2012	2.00±0.15	1.25±0.15	0.50±0.15	0.38±0.20	0.38±0.20
05	RM3216	3.20±0.15	1.60±0.15	0.55±0.15	0.38±0.20	0.38±0.20
05	RM3225	3.20±0.20	2.50±0.20	0.55±0.15	0.50±0.25	0.50±0.25
05	RM5025	5.00±0.15	2.50±0.15	0.55±0.15	0.60±0.25	0.60±0.25
05	RM6332	6.30±0.15	3.20±0.15	0.55±0.15	0.60±0.25	0.60±0.25
06	RMHT1005	1.00±0.15	0.50±0.10	0.35±0.10	0.20±0.15	0.25±0.10
06	RMHT1608	1.60±0.15	0.80±0.15	0.50±0.15	0.30±0.15	0.30±0.15
06	RMHT2012	2.00±0.20	1.25±0.20	0.55±0.10	0.38±0.20	0.38±0.20
06	RMHT3216	3.20±0.20	1.60±0.20	0.60±0.10	0.38±0.25	0.38±0.25
06	RMHT3225	3.20±0.20	2.50±0.20	0.60±0.20	0.50±0.25	0.50±0.25
06	RMHT5025	5.00±0.20	2.50±0.20	0.60±0.20	0.60±0.25	0.60±0.25
06	RMHT6332	6.30±0.20	3.20±0.20	0.60±0.20	0.60±0.25	0.60±0.25
07, 08, 12, 13, 14	RMK1005	1.00±0.20	0.50±0.10	0.25~0.84	0.20±0.10	0.25±0.10
07, 08, 12, 13, 14	RMK1608	1.60±0.15	0.80±0.15	0.25~0.84	0.30±0.20	0.30±0.15
07, 08, 12, 13, 14	RMK2012	2.00±0.15	1.25±0.15	0.38~0.84	0.38±0.15	0.38±0.13
07, 08, 12, 13, 14	RMK3216	3.20±0.20	1.60±0.13	0.38~0.84	0.38±0.13	0.38±0.13
07, 08, 12, 13, 14	RMK3225	3.20±0.15	2.50±0.15	0.38~0.84	0.50±0.25	0.50±0.25
07, 14	RMK5025/5225	5.00±0.15	2.50±0.15	0.38~0.84	0.60±0.15	0.60±0.15
07, 08, 12, 13, 14	RMK6332	6.30 +0.25/-0.15	3.20±0.15	0.38~0.84	0.60±0.15	0.60±0.15
08, 12, 13	RMK5025	5.00±0.15	2.50±0.15	0.38~0.84	0.60±0.15	0.60±0.15
09	RMS6363A	6.35±0.25	6.35±0.25	1 +0.2/-0.1	0.25 (not assessed)	2.00±0.25

Ref.	Model	L	W	H	M	N
09	RMS7142A	7.10±0.25	4.20±0.25	2 +0.25/-0.1	0.2 (not assessed)	2.00±0.25
09	RMS4271A	4.20±0.25	7.15±0.25	2 +0.25/-0.1	0.2 (not assessed)	1.60±0.25
11	RM1608	1.50±0.10	0.80±0.10	0.40±0.08	0.25±0.10	—
15	RMKH1005	1.00±0.10	0.50±0.10	0.35±0.10	0.25±0.10	0.25±0.10
15	RMKH1608	1.60±0.15	0.80±0.15	0.50±0.15	0.30±0.15	0.30±0.15
15	RMKH2012	2.03±0.15	1.27±0.13	0.50±0.10	0.38±0.15	0.38±0.15
15	RMKH3216	3.20±0.20	1.60±0.13	0.60±0.10	0.38±0.20	0.38±0.20
15	RMKH3225	3.20±0.15	2.50±0.15	0.55±0.15	0.50±0.25	0.50±0.25
15	RMKH5225/5025	5.20 +0.00/-0.35	2.50±0.15	0.55±0.15	0.60±0.25	0.60±0.25
15	RMKH6332	6.30 +0.25/-0.15	3.20±0.15	0.55±0.15	0.60±0.25	0.60±0.25
16	RMS1005	1.00±0.15 0	.50±0.10	0.35±0.10	0.20±0.15	0.25±0.10
16	RMS1608	1.60±0.15 0	.80±0.15	0.50±0.15	0.30±0.15	0.30±0.15
16	RMS2012	2.00±0.20 1	.25±0.20	0.55±0.15	0.38±0.20	0.38±0.20
16	RMS3216	3.20±0.20 1	.60±0.20	0.60±0.20	0.38±0.25	0.38±0.25
16	RMS3225	3.20±0.20 2	.50±0.20	0.60±0.20	0.50±0.25	0.50±0.25
16	RMS5025	5.00±0.20 2	.50±0.20	0.60±0.20	0.60±0.25	0.60±0.25
16	RMS6332	6.30±0.20 3	.20±0.20	0.60±0.20	0.60±0.25	0.60±0.25
17, 18	RMZ1005	1.00±0.20	0.50±0.10	0.25~0.84	0.20±0.10	0.25±0.10
17, 18	RMZ1608	1.60±0.15	0.80±0.15	0.25~0.84	0.30±0.20	0.30±0.15
17, 18	RMZ2012	2.00±0.15	1.25±0.15	0.50±0.15	0.38±0.15	0.38±0.13
17, 18	RMZ3216	3.20±0.20	1.60±0.13	0.38~0.84	0.38±0.13	0.38±0.13
17, 18	RMZ3225	3.20±0.15	2.50±0.15	0.38~0.84	0.50±0.25	0.50±0.25
17, 18	RMZ5025	5.00±0.15	2.50±0.15	0.38~0.84	0.60±0.15	0.60±0.15
17, 18	RMZ6332	6.30 +0.25/-0.15	3.20±0.15	0.38~0.84	0.60±0.15	0.60±0.15
19	RMHV1608	1.60±0.20	0.80±0.20	0.50±0.15	0.30±0.20	0.30±0.15
19	RMHV2012	2.00±0.20	1.25±0.20	0.50±0.15	0.40±0.25	0.30±0.15
19	RMHV3216	3.20±0.20	1.60±0.20	0.50±0.20	0.30±0.15	0.40±0.20
19	RMHV3225	3.20±0.20	2.50±0.20	0.60±0.20	0.30±0.15	0.40±0.20
19	RMHV5025	5.00±0.20	2.50±0.20	0.60±0.20	0.50±0.30	0.50±0.30
19	RMHV6332	6.30±0.20	3.10±0.20	0.60±0.20	0.50±0.30	0.50±0.30

The RMKH dimension table names RMKH5225/5025 with L=5.20 +0.00/-0.35 mm, while its rating table names RMKH5025. Confirm the model/package correspondence when ordering.

03 / SERIES TECHNICAL DATA

Power derating and operating conditions



Vertical axis: rated power %. Horizontal axis: temperature °C. Applicability below.

Ref.	100% power knee / °C	Zero power / °C	Temperature reference
01 / 04 / 10 / 16 / 19	70	125	Ambient temperature
02 / 03 / 05 / 07 / 08 / 09 / 12 / 13 / 14 / 15 / 17 / 18	70	150	Ambient; source-curve nodes
06	150	200	Ambient temperature
11 (0.09 W)	70	150	Mounting-surface temperature
11 (0.5 W)	100	150	Mounting-surface temperature

Curves are redrawn from the source nodes. Derate linearly between the knee and zero-power temperature. Curve limits, operating limits and qualification temperatures serve different purposes and remain family-specific.

Heat dissipation and high-voltage assembly

Family 01 requires thermal design or auxiliary cooling to keep maximum operating body surface temperature at or below 150 °C. Family 11 ratings use mounting-surface temperature. For family 19, use low-residue solder paste and clean both surfaces and the component-to-PCB gap. Apply insulation, such as insulating-oil coating or potting, to prevent discharge in humid or low-pressure environments.

04 / SERIES TECHNICAL DATA

Qualification conditions and acceptance criteria

Identical test conditions and criteria are consolidated by test item. Reference numbers define applicability. K/M and Y/E/H identify source characteristic columns. Numerical criteria generally mean |ΔR|≤a%R+b Ω; retain both terms and the stated conditions.

Ref.	Meaning of numerical criteria columns
01 / 02 / 04 / 05 / 07 / 08 / 10 / 11 / 12 / 13 / 14 / 15	|ΔR| ≤ listed value %R + 0.01 Ω, except TCR/text criteria
16	|ΔR| ≤ listed value %R + 0.05 Ω, except text criteria
03 / 06 / 09 / 17 / 18 / 19	Use the complete criterion in the table; Rmax is zero-ohm maximum resistance

Ref.	Test item	Criterion / characteristic	Conditions and method
13	DPA	Char. K: No defects or abnormalities defined by the standard; Char. M: No defects or abnormalities defined by the standard	GJB 4027A-2006, work item 0103
13	Consistency	Char. K: SD <0.6%; -0.6%<mean<0.5%; Char. M: SD <0.6%; -0.6%<mean<0.5%	Within a lot: sample and calculate SD; across lots: sample each lot and calculate the mean
01, 04, 10	Low-temperature operation	Char. K: 0.5; Char. M: 0.5	-55 °C, UR (≤Umax); 45(+5/-0) min on, 15(+5/-0) min off
02	Low-temperature operation	Char. K: 0.5; Char. M: 0.5	-65 °C, UR (≤Umax); 45(+5/-0) min on, 15(+5/-0) min off
03	Low-temperature operation	No mechanical damage; ΔR≤Rmax	-65 °C, IR, 45 min
05	Low-temperature operation	Char. Y: 0.2; Char. E: 0.25; Char. H: 0.25	-55 °C, UR (≤Umax), 45(+5/-0) min on, 15(+5/-0) min off
06	Low-temperature operation	ΔR≤±(0.5%R+0.01 Ω)	-55 °C, UR (≤Umax), 45(+5/-0) min
07, 11, 13, 14	Low-temperature operation	Char. K: 0.25; Char. M: 0.5	-65 °C, UR (≤Umax); 45(+5/-0) min on, 15(+5/-0) min off
08	Low-temperature operation	Char. E: 0.1; Char. H: 0.25	-65 °C, UR (≤Umax), 45(+5/-0) min on, 15(+5/-0) min off
09	Low-temperature operation	No visual or mechanical damage; ΔR≤±(0.5%R+0.01 Ω)	-65(+0/-5) °C, powered for 45 min
12	Low-temperature operation	Char. K: 0.25; Char. M: 0.5	-65 °C, UR (≤Umax), 45 min; 45(+5/-0) min on, 15(+5/-0) min off
15	Low-temperature operation	Char. K: 0.25; Char. M: 0.5	-65 °C, UR (≤Umax), 45(+5/-0) min
17, 18	Low-temperature operation	No mechanical damage; ΔR≤Rmax	-65 °C, IR; 45(+5/-0) min on, 15(+5/-0) min off
19	Low-temperature storage	ΔR≤±(0.5%R+0.01 Ω)	(-65±5) °C, (24±4) h

Ref.	Test item	Criterion / characteristic	Conditions and method
13	Shock	Char. K: 0.5; Char. M: 0.5	Peak 100 g, terminal-peak sawtooth, 2.96 m/s, 6 ms pulse, 3 shocks along Y
16	Shock	1.0	Half-sine, 100 g, 6 ms, 3.75 m/s
13	Power conditioning	Char. K: 0.5; Char. M: 0.5	70 °C, 100 h, 1.225UR (≤Umax)
03, 17	Solderability	Electrode solder coverage 95%	245 °C, 5 s
04	Solderability	Char. K: Electrode solder coverage ≥95%; Char. M: Electrode solder coverage ≥95%	Steam ageing for 1 h, 245 °C, 5 s
05	Solderability	Char. Y: Electrode solder coverage ≥95%; Char. E: Electrode solder coverage ≥95%; Char. H: Electrode solder coverage ≥95%	Steam ageing 1 h, 245 °C, 5 s
06, 19	Solderability	Solder coverage ≥95%	(235±5) °C, (5±1) s
07, 12, 14	Solderability	Char. K: 95% electrode solder coverage; Char. M: 95% electrode solder coverage	245 °C, 5 s, steam ageing for 1 h
08	Solderability	Char. E: Electrode solder coverage ≥95%; Char. H: Electrode solder coverage ≥95%	Steam ageing 1 h, 245 °C, 5 s
13	Solderability	Char. K: 95% electrode solder coverage; Char. M: 95% electrode solder coverage	245 °C, 5 s; ageing condition 1a: 1 h steam ageing
15	Solderability	Char. K: Electrode solder coverage ≥95%; Char. M: Electrode solder coverage ≥95%	245 °C, 5 s
18	Solderability	Electrode solder coverage 95%	Steam ageing 1 h; 245 °C, 5 s
16	Substrate bending strength	1.0	5025/6332: 2 mm; others: 3 mm; 60 s
07, 12, 14	Failure-rate qualification	Char. K: 2.0; Char. M: 2.0	70 °C, UR (≤Umax), 10000 h
13	Failure-rate qualification	Char. K: 0.5; Char. M: 0.5	70 °C, UR (≤Umax), 10000 h
01	Life	Char. K: 2.0; Char. M: 2.0	70 °C, UR (≤Umax), 2000 h (RM6363: 1000 h)
02, 04, 10	Life	Char. K: 2.0; Char. M: 2.0	70 °C, UR (≤Umax), 2000 h
03, 17, 18	Life	No mechanical damage; R≤Rmax	70 °C, IR, 2000 h
05	Life	Char. Y: 0.5; Char. E: 0.5; Char. H: 0.5	70 °C, UR (≤Umax), 2000 h
06	Life	ΔR≤±(2.0%R+0.05 Ω)	150 °C, UR (≤Umax), 1000 h
07, 14	Life	Char. K: 0.5; Char. M: 2.0	70 °C, UR (≤Umax), 2000 h
08	Life	Char. E: 0.5; Char. H: 0.5	70 °C, UR (≤Umax), 2000 h
09	Life	No visual or mechanical damage; ΔR≤±(2%R+0.01 Ω)	Rated power, 1000 h

Ref.	Test item	Criterion / characteristic	Conditions and method
11	Life	Char. K: 0.5; Char. M: 2	70 °C, UR (≤Umax), 1000 h (RM1608-0.09W: 2000 h)
12	Life	Char. K: 0.5; Char. M: 1.5	70 °C, UR (≤Umax), 2000 h
13	Life	Char. K: 0.5; Char. M: 0.5	70 °C, UR (≤Umax), 2000 h
15	Life	Char. K: 0.5; Char. M: 2	70 °C, UR (≤Umax), 2000 h
19	Life	ΔR≤±(5.0%R+0.05 Ω)	UR (≤Umax), 1000 h
16	Termination strength	No visible damage	1005: 10 N; 1608 and larger: 17.7 N; 60 s
01, 02, 04, 10	Thermal shock	Char. K: 0.5; Char. M: 0.5	-55 °C to +125 °C, 5 cycles
03, 17	Thermal shock	No mechanical damage; R≤Rmax	-65 °C to 150 °C, 5 cycles
05	Thermal shock	Char. Y: 0.1; Char. E: 0.1; Char. H: 0.25	-55 °C to +125 °C, 5 cycles
06	Thermal shock	ΔR≤±(0.5%R+0.01 Ω)	-55 °C to 150 °C, 5 cycles
07, 11, 12, 13, 14	Thermal shock	Char. K: 0.5; Char. M: 0.5	-65 °C to +150 °C, 5 cycles
08	Thermal shock	Char. E: 0.1; Char. H: 0.1	-65 °C to +150 °C, 5 cycles
09	Thermal shock	No visual or mechanical damage; ΔR≤±(0.5%R+0.01 Ω)	-65(+0/-5) °C to 150(+5/-0) °C, 5 cycles
15	Thermal shock	Char. K: 0.5; Char. M: 0.5	-65 °C to 150 °C, 5 cycles
16	Thermal shock	1.0	-55 °C to 125 °C, 1000 cycles
18	Thermal shock	No mechanical damage; R≤Rmax	-65 °C to 150 °C, 100 cycles
19	Thermal shock	ΔR≤±(0.5%R+0.01 Ω)	-55 °C to 125 °C, 5 cycles
13	Thermal shock, 100 cycles	Char. K: 0.5; Char. M: 0.5	-65 °C to +150 °C, 100 cycles
13	Thermal-vacuum outgassing	Char. K: Total mass loss <1.00%; collected condensable volatiles <0.10%; Char. M: Total mass loss <1.00%; collected condensable volatiles <0.10%	125 °C, vacuum ≤7×10^-3 Pa, 24 h
01	Temperature coefficient	Char. K: ±100ppm/K; Char. M: ±300ppm/K	-55 °C to +125 °C
02, 04, 10	Temperature coefficient	Char. K: ±100×10^-6/ K; Char. M: ±300×10^-6/ K	-55 °C to +125 °C
05	Temperature coefficient	Char. Y: ±10ppm/K; Char. E: ±25ppm/K; Char. H: ±50ppm/K	-55 °C to +125 °C
07, 12, 14	Temperature coefficient	Char. K: ±100×10^-6/ K; Char. M: ±300×10^-6/ K	25 °C, -55 °C, 25 °C, 125 °C
08	Temperature coefficient	Char. E: ±25ppm/K; Char. H: ±50ppm/K	-55 °C to +125 °C
11	Temperature coefficient	Char. K: ±100ppm/K; Char. M: ±300ppm/K	-55 °C, 125 °C

Ref.	Test item	Criterion / characteristic	Conditions and method
13	Temperature coefficient	Char. K: ±100ppm/K; Char. M: ±300ppm/K	25 °C, -65 °C, 25 °C, 150 °C
15	Temperature coefficient	Char. K: ±100ppm/K; Char. M: ±300ppm/K	-55 °C to 125 °C
09	Salt spray	Corroded termination area ≤5%; markings clear and complete	48 h
01	Short-time overload	Char. K: 0.5; Char. M: 0.5	2.5UR (≤2Umax), 5 s; RM5025/RM6332/RM6363: 5 times rated power, 5 s
02, 04, 10	Short-time overload	Char. K: 0.5; Char. M: 0.5	2.5UR (≤2Umax), 5 s
03, 17, 18	Short-time overload	No arcing, burning or charring; R≤Rmax	2.5IR, 5 s
05	Short-time overload	Char. Y: 0.1; Char. E: 0.1; Char. H: 0.1	2.5UR (≤2Umax), 5 s
06	Short-time overload	ΔR≤±(0.5%R+0.01 Ω)	2.5UR (≤Umax), 5 s
07, 11, 12, 13, 14, 15	Short-time overload	Char. K: 0.25; Char. M: 0.5	2.5UR (≤2Umax), 5 s
08	Short-time overload	Char. E: 0.1; Char. H: 0.1	2.5UR (≤2Umax), 5 s
01	Sulfur test	Char. K: 1.0; Char. M: 1.0	105 °C, damp-heat sulfur-powder vapour test (with saturated potassium nitrate), 1000 h (no sulfur-resistance requirement for RM6363)
02, 10, 14	Sulfur test	Char. K: 1.0; Char. M: 1.0	105 °C, damp-heat sulfur-powder vapour test (with saturated potassium nitrate), 1000 h
03, 17	Sulfur test	R≤Rmax	105 °C, damp-heat sulfur-powder vapour test (with saturated potassium nitrate), 1000 h
16	Sulfur test	1.0	105 °C, damp-heat sulfur-powder vapour test (with saturated potassium nitrate), 750 h
16	Damp heat, steady state	2.0	85 °C, RH85%, 10%UR (≤Umax), 1000 h
19	Insulation resistance	≥10 GΩ	Applied voltage 500 V
01	Moisture resistance	Char. K: 1.0; Char. M: 0.5/1.0	65 °C, RH 80% to 100%, 10 cycles
02, 04, 10	Moisture resistance	Char. K: 1.0; Char. M: 1.0	65 °C, RH 80% to 100%, 10 cycles
03, 17, 18	Moisture resistance	No electrical or mechanical damage; R≤Rmax	65 °C, RH80% to 100%
05	Moisture resistance	Char. Y: 0.4; Char. E: 0.4; Char. H: 0.4	65 °C, RH80% to 100%
06	Moisture resistance	ΔR≤±(1.0%R+0.01 Ω)	65 °C, RH80% to 100%
07, 11, 12, 14	Moisture resistance	Char. K: 0.5; Char. M: 0.5	25 °C to 65 °C, RH 80% to 100%, 10 cycles
08	Moisture resistance	Char. E: 0.2; Char. H: 0.4	65 °C, RH80% to 100%
09	Moisture resistance	No visual or mechanical damage; ΔR≤±(1%R+0.01 Ω)	25 °C to 65 °C, RH80% to 100%, 10 cycles (240 h)

Ref.	Test item	Criterion / characteristic	Conditions and method
13	Moisture resistance	Char. K: 0.5; Char. M: 0.5	65 °C, RH 80% to 100%
15	Moisture resistance	Char. K: 0.5; Char. M: 0.5	65 °C, RH80% to 100%
19	Moisture resistance	ΔR≤±(2.0%R+0.01 Ω)	10 °C to 65 °C, RH90% to 100%
01	Resistance to soldering heat	Char. K: 0.5; Char. M: 0.25/0.5	3 cycles; first mounting at 245 °C; next 2 cycles: 235 °C, 30 s
02, 04, 10	Resistance to soldering heat	Char. K: 0.5; Char. M: 0.5	3 cycles; first cycle: reflow at 245 °C for 2 to 5 s; next 2 cycles: 235 °C, 30 s
03	Resistance to soldering heat	No mechanical damage, peeling or erosion of metallization; ΔR≤Rmax	235 °C, 30 s, 3 cycles
05	Resistance to soldering heat	Char. Y: 0.2; Char. E: 0.25; Char. H: 0.25	3 cycles; first: reflow at 245 °C for 2 to 5 s; next 2: 235 °C, 30 s
06	Resistance to soldering heat	ΔR≤±(0.5%R+0.01 Ω)	(235±5) °C, (30±5) s, 3 times
07, 12, 13, 14	Resistance to soldering heat	Char. K: 0.25; Char. M: 0.25	3 cycles; first cycle: reflow at 245 °C for 2 to 5 s; next 2 cycles: 235 °C, 30 s
08	Resistance to soldering heat	Char. E: 0.2; Char. H: 0.25	3 cycles; first: reflow at 245 °C for 2 to 5 s; next 2: 235 °C, 30 s
15	Resistance to soldering heat	Char. K: 0.25; Char. M: 0.25	235 °C, 30 s, 3 cycles
17, 18	Resistance to soldering heat	No mechanical damage, peeling or erosion of metallization; ΔR≤Rmax	3 cycles; first: reflow at 245 °C, 2 to 5 s; next 2: 235 °C, 30 s
19	Resistance to soldering heat	ΔR≤±(0.25%R+0.01 Ω)	(235±5) °C, (30±5) s, twice
11	Connection exposure	Char. K: 0.25; Char. M: 0.25	After bonding installation, stabilize at room temperature
09	Pulse test	No sparks, arcing, burning or charring; ΔR≤±(5%R+0.01 Ω)	See Electrical Specifications
16	Overload	2.0	2.5UR (≤maximum overload voltage), 5 s
02, 04, 10	Solder mounting strength	Char. K: No mechanical damage; Char. M: No mechanical damage	Thrust: 1005, 10 N; 1608/2012/3216/3225, 20 N; 5025/6332/3263/4225/6308, 30 N; 30 s
03	Solder mounting strength	No mechanical damage	0603G: 3 N; 1005: 7.5 N; 1608: 10 N; 2012/3216/3225: 20 N; 5025/6332: 30 N; 30 s
07, 14	Solder mounting strength	Char. K: No mechanical damage; Char. M: No mechanical damage	Thrust: 1005, 10 N; 1608/2012/3216, 20 N; 3225/5025/5225/6332, 30 N; 30 s
09	Solder mounting strength	No visual or mechanical damage	50 N, 30 s
12, 13, 15	Solder mounting strength	Char. K: No mechanical damage; Char. M: No mechanical damage	Thrust: 1005, 10 N; 1608/2012/3216, 20 N; 3225/5025/6332, 30 N; 30 s
17, 18	Solder mounting strength	No mechanical damage	1005: 7.5 N; 1608: 10 N; 2012/3216/3225: 20 N; 5025/6332: 30 N; 30 s
11	Bond mounting strength	Char. K: No mechanical damage; Char. M: No mechanical damage	0.03 N, 30 s

Ref.	Test item	Criterion / characteristic	Conditions and method
13	Random vibration	Char. K: 0.5; Char. M: 0.5	Power spectral density 0.02 g²/Hz, Y axis, 15 min
16	Electrostatic discharge	3.0	1005/1608: 1 kV; 2012 and larger: 2 kV
16	High-temperature life	2.0	70 °C, UR (≤Umax), 1000 h, 1.5 h on/0.5 h off
01, 02, 04, 10	High-temperature exposure	Char. K: 1.0; Char. M: 1.0	150 °C, 100 h
03, 17, 18	High-temperature exposure	No mechanical damage; R≤Rmax	150 °C, 100 h
05	High-temperature exposure	Char. Y: 0.2; Char. E: 0.2; Char. H: 0.2	150 °C, 100 h
06	High-temperature exposure	ΔR≤±(1.0%R+0.01 Ω)	(150±5) °C, (100±4) h
07, 11, 12, 13, 14, 15	High-temperature exposure	Char. K: 0.5; Char. M: 1.0	150 °C, 100 h
08	High-temperature exposure	Char. E: 0.1; Char. H: 0.2	150 °C, 100 h
09	High-temperature exposure	No visual or mechanical damage; ΔR≤±(1%R+0.01 Ω)	(150±5) °C, (100±5) h
16	High-temperature exposure	1.0	150 °C, 1000 h, unpowered
16	High-frequency vibration	1.0	10 to 2000 Hz, displacement amplitude 0.75 mm, 5 g, 12×3=36 times

Source expressions R≤Rmax and ΔR≤Rmax are retained separately. Some family 01 M-characteristic limits are listed as 0.25/0.5 or 0.5/1.0; confirm the model-specific applicability against the procurement specification.

05 / SERIES TECHNICAL DATA

Ordering, grades and source index

Specify the family reference, original model, technology, grade, power, resistance, tolerance, TCR and termination. Identical size codes can carry different ratings across technologies and grades.

Ref.	Family	Ordering examples and fields
01	RM power thick film	RM3225-1WA-MBP472F / RM6363-6WMB101J Model / Power / Product code (RM3225: A; others: none) / Characteristic K or M / Termination B (wraparound solder), P (sulfur-resistant; omit P when not required) / E24 or E96 nominal resistance / Tolerance. F: ±1%; G: ±2%; J: ±5%; K: ±10%.
02	RM anti-sulfur thick film	RM1608MBG472F Model / Characteristic K or M / Termination BG / Nominal resistance (E24, E96 series; range in table) / Tolerance F (±1%), G (±2%), J (±5%) K: characteristic K; M: characteristic M. B: wraparound solder termination; G: anti-sulfur.
03	RM anti-sulfur zero-ohm	RM2012BGC50 Model / Termination BG: B solder, G internal gold electrode of solder termination / Grade C / 50 (maximum resistance 50 mΩ))%(rewop detaR
04	RM standard thick film	RM1608MB472F Model / Characteristic K or M / Termination B / Nominal resistance (E24, E96 series; range in table) / Tolerance F (±1%), G (±2%), J (±5%) K: characteristic K; M: characteristic M. B: solder termination.
05	RM thin film	RM1608HB472B Model / Characteristic Y, E or H / Termination B (solder) / E24 or E96 nominal resistance / Tolerance Y±10, E±25, H±50ppm/K; W±0.05%, B±0.1%, C±0.25%, D±0.5%, F±1%.
06	RMHT high-temperature thick film	RMHT6332MB101J Model / TCR C±100 or M±300ppm/K / B wraparound solder termination / Nominal resistance / F±1%, G±2%, J±5%)%(rewop detaR
07	RMK GJB thick film	RMK2012MB472FM Model / Characteristic K or M / Termination B (solder) / Nominal resistance (E24, E96 series; range in table) / Resistance tolerance / Failure-rate level F: ±1%; G: ±2%; J: ±5%. M: 1.0%/1000 h (level 5); P: 0.1%/1000 h (level 6).
08	RMK GJB thin film	RMK2012HB472FM Model / Characteristic E or H / Termination B (solder) / E24 or E96 nominal resistance / Tolerance / Failure-rate level M: 1.0%/1000 h (level 5) E±25, H±50ppm/K; W±0.05%, B±0.1%, C±0.25%, D±0.5%.
09	RMS pulse / surge	RMS6363A-M-B-300-J Model / M±300ppm/K / B wraparound solder termination / Nominal resistance 1 Ω to 30 Ω / J±5%)%(rewop detaR
10	RM sulfur-resistant thick film	RM1608MBP472F Model / Characteristic K or M / Termination BP / Nominal resistance (E24, E96 series; range in table) / Tolerance F (±1%), G (±2%), J (±5%) K: characteristic K; M: characteristic M. B: solder termination; P: sulfur-resistant.
11	RM1608 gold-electrode chip	RM1608-0.09W-MW472FW Model / Power (0.09 W, 0.5 W) / Characteristic K or M / Termination W (single-sided metal-wire bonding) / E24 or E96 nominal resistance / Tolerance / Packaging. Tolerance: F±1%, G±2%, J±5%. Packaging: B, bag; T, tape; W, biscuit box.)%(rewop detaR
12	RMK space-grade YC thick film	RMK1608 - K - B - 103 - F - M Model / Characteristic K or M / Termination B (solder) / Nominal resistance (E24, E96 series; range in table) / Resistance tolerance / Failure-rate level D: ±0.5%; F: ±1%; G: ±2%; J: ±5%. M: 1.0%/1000 h (level 5); P: 0.1%/1000 h (level 6).
13	RMK YG-grade thick film	RMK2012 - M - B - 472 - F - R - K+ Model / Characteristic K or M / Termination B (solder) / Nominal resistance (E24, E96 series; range in table) / Resistance tolerance / Failure-rate level / Management mark K+ F: ±1%; G: ±2%; J: ±5%. R: 0.01%/1000 h (level 7); K+: management mark for products supplied to the First Academy of Aerospace.
14	RMK GJB sulfur-resistant thick film	RMK2012MBP472FM Model / Characteristic K or M / Termination B (solder), P (sulfur-resistant, may be omitted) / Nominal resistance (E24, E96 series; range in table) / Resistance tolerance / Failure-rate level F: ±1%; G: ±2%; J: ±5%. M: 1.0%/1000 h (level 5); P: 0.1%/1000 h (level 6).

Ref.	Family	Ordering examples and fields
15	RMKH precision / reliability	RMKH2012MB472BM Model / Characteristic K or M / B solder termination / E24 or E96 nominal resistance / B±0.1%, C±0.25%, D±0.5% / Failure-rate level M 1.0%/1000 h (level 5), P 0.1%/1000 h (level 6)
16	RMS automotive surge	RMS6332-2W-S-B-101-F Model / Power (see table) / TCR S±100 or U±250×10^-6/ °C / B solder termination / E24 or E96 nominal resistance / F±1%, G±2%, J±5%
17	RMZ GJB sulfur-resistant zero-ohm	RMZ2012BPH20 Model / Termination BP: B solder, P sulfur-resistant (may be omitted) / Grade H / Maximum resistance: 20, 25 or 30 mΩ)%(rewop detaR
18	RMZ space-grade YC zero-ohm	RMZ3216-B-T-25 Model / Termination B (solder) / Grade T / Maximum resistance: 20, 25 or 30 mΩ)%(rewop detaR
19	RMHV high voltage	RMHV6332DB307J Model / Limit voltage C 2000 V, D 4000 V, E 300 V, F 400 V, G 2500 V, H 3000 V / B wraparound solder termination / Nominal resistance / G±2%, J±5%, K±10%

Applicable grades and specifications

Ref.	Family	Grades / specifications stated in source
01	RM power thick film	Quality grade: inverted triangle G mark, J. Generic specification: GJB 1432B-2009. Detail specifications: first 6 types, Q/RU 26043-2021; RM6363-4W/6W, Q/RU 21432.102-2025.
02	RM anti-sulfur thick film	Quality grade: inverted triangle G mark, J. Generic specification: GJB 1432B-2009. RM1005 ~ RM3263 Q/RU 26034-2018
03	RM anti-sulfur zero-ohm	Quality grade: inverted triangle G mark, J. Detail specification: Q/RU 26787.8-2026. Generic specification: GJB 6787-2009.
04	RM standard thick film	Quality grade: inverted triangle G mark, J. Generic specification: GJB 1432B-2009. RM1005 1.00±0.15 0.50±0.10 0.35±0.10 0.20±0.15 0.25±0.10 0.05 30 Q/RU 21432.34-2013 RM1608 1.60±0.15 0.80±0.15 0.50±0.15 0.30±0.15 0.30±0.15 0.1 50 Q/RU 21432.35-2013 RM2012 2.00±0.20 1.25±0.20 0.55±0.20 0.38±0.20 0.38±0.20 0.15 50 Q/RU 21432.36-2013 RM3216 3.20±0.20 1.60±0.20 0.60±0.20 0.38±0.25 0.38±0.25 0.25 100 Q/RU 21432.37-2013 RM3225 3.20±0.20 2.50±0.20 0.60±0.20 0.50±0.25 0.50±0.25 0.5 150 Q/RU 21432.38-2013 RM5025 5.00±0.20 2.50±0.20 0.60±0.20 0.60±0.25 0.60±0.25 0.8 150 Q/RU 21432.39-2013 RM6332 6.30±0.20 3.20±0.20 0.60±0.20 0.60±0.25 0.60±0.25 1 150 Q/RU 21432.40-2013 RM4225 4.20±0.20 2.50±0.20 1.05±0.20 0.70±0.20 1.20±0.15 1 200 Q/RU 21432.41-2013 RM6308 6.30±0.20 3.20±0.20 0.90±0.20 0.60±0.25 0.65±0.25 2 200 Q/RU 21432.42-2013 RM3263 3.20±0.15 6.30±0.30 1.05±0.25 0.50±0.25 0.60±0.25 3 200 Q/RU 21432.43-2013
05	RM thin film	Generic specification: GJB 1432B-2009. Quality grade: inverted triangle G mark, J. RM1005 1.00±0.15 0.50±0.10 0.30±0.15 0.25±0.10 0.25±0.10 Q/RU 21432.105-2014 RM1608 1.60±0.15 0.80±0.15 0.45±0.15 0.30±0.15 0.30±0.15 Q/RU 21432.106-2014 RM2012 2.00±0.15 1.25±0.15 0.50±0.15 0.38±0.20 0.38±0.20 Q/RU 21432.107-2014 RM3216 3.20±0.15 1.60±0.15 0.55±0.15 0.38±0.20 0.38±0.20 Q/RU 21432.108-2014 RM3225 3.20±0.20 2.50±0.20 0.55±0.15 0.50±0.25 0.50±0.25 Q/RU 21432.109-2014 RM5025 5.00±0.15 2.50±0.15 0.55±0.15 0.60±0.25 0.60±0.25 Q/RU 21432.110-2014 RM6332 6.30±0.15 3.20±0.15 0.55±0.15 0.60±0.25 0.60±0.25 Q/RU 21432.111-2014
06	RMHT high-temperature thick film	Quality grade: J. Detail specification: Q/RU 26117-2023. Generic specification: GJB
07	RMK GJB thick film	Quality grade: Triangle J mark; CAST B; SAST; RMK6332 ZZR-Q/RU 21432.4A-2012 For CAST, SAST and LMS products, refer to the corresponding procurement specifications. RMK1005 ZZR-Q/RU 21432.5-2012 RMK1608 ZZR-Q/RU 21432.6A-2012 RMK2012 ZZR-Q/RU 21432.1A-2012 RMK3216 ZZR-Q/RU 21432.2A-2012 RMK3225 ZZR-Q/RU 21432.7A-2012 RMK5025/5225 ZZR-Q/RU 21432.3A-2012

Ref.	Family	Grades / specifications stated in source
08	RMK GJB thin film	Generic specification: GJB 1432B-2009. Quality grade: GJB, SAST, GJB(M)/K, QJB(M)/K. Refer to corresponding procurement specifications for SAST and LMS products. RMK1005 1.00±0.20 0.50±0.10 0.25~0.84 0.20±0.10 0.25±0.10 ZZR-Q/RU 21432.5-2012 RMK1608 1.60±0.15 0.80±0.15 0.25~0.84 0.30±0.20 0.30±0.15 ZZR-Q/RU 21432.6A-2012 RMK2012 2.00±0.15 1.25±0.15 0.38~0.84 0.38±0.15 0.38±0.13 ZZR-Q/RU 21432.1A-2012 RMK3216 3.20±0.20 1.60±0.13 0.38~0.84 0.38±0.13 0.38±0.13 ZZR-Q/RU 21432.2A-2012 RMK3225 3.20±0.15 2.50±0.15 0.38~0.84 0.50±0.25 0.50±0.25 ZZR-Q/RU 21432.7A-2012 RMK5025 5.00±0.15 2.50±0.15 0.38~0.84 0.60±0.15 0.60±0.15 ZZR-Q/RU 21432.3A-2012 RMK6332 3.20±0.15 0.38~0.84 0.60±0.15 0.60±0.15 ZZR-Q/RU 21432.4A-2012
09	RMS pulse / surge	Quality grade: J. Detail specification: Q/RU 26090-2023. Generic specification: GJB
10	RM sulfur-resistant thick film	Quality grade: inverted triangle G mark, J. Generic specification: GJB 1432B-2009. RM1005 ~ RM3263 Q/RU 26035-2018
11	RM1608 gold-electrode chip	Quality grade: inverted triangle G mark, J. Detail specification: Q/RU 26115-2024. Generic specification: GJB 1432C-2021.
12	RMK space-grade YC thick film	Quality grade: YB, YC. Generic specification: GJB RMK1005 Q/QJA 20087/1A-2019 RMK1608 Q/QJA 20087/1A-2019 RMK2012 Q/QJA 20087/1A-2019 RMK3216 Q/QJA 20087/1A-2019 RMK3225 Q/QJA 20087/1A-2019 RMK5025 Q/QJA 20087/1A-2019 RMK6332 Q/QJA 20087/1A-2019
13	RMK YG-grade thick film	Quality grade: Triangle YG mark. Generic RMK6332 ZZR-Q/RU 21432.4B-2015 RMK1005 ZZR-Q/RU 21432.5A-2015 RMK1608 ZZR-Q/RU 21432.6B-2015 RMK2012 ZZR-Q/RU 21432.1B-2015 RMK3216 ZZR-Q/RU 21432.2B-2015 RMK3225 ZZR-Q/RU 21432.7B-2015 RMK5025 ZZR-Q/RU 21432.3B-2015
14	RMK GJB sulfur-resistant thick film	Quality grade: Triangle J mark. Generic RMK6332 ZZR-Q/RU 21432.4C-2023 RMK1005 ZZR-Q/RU 21432.5B-2023 RMK1608 ZZR-Q/RU 21432.6C-2023 RMK2012 ZZR-Q/RU 21432.1C-2023 RMK3216 ZZR-Q/RU 21432.2C-2023 RMK3225 ZZR-Q/RU 21432.7C-2023 RMK5025/5225 ZZR-Q/RU 21432.3C-2023
15	RMKH precision / reliability	Quality grades: QJB, J. Generic specification: GJB 1432B-2009. Detail specifications are RMKH1005 1.00±0.10 0.50±0.10 0.35±0.10 0.25±0.10 0.25±0.10 ZZR-Q/RU 21432.19-2012 RMKH1608 1.60±0.15 0.80±0.15 0.50±0.15 0.30±0.15 0.30±0.15 ZZR-Q/RU 21432.17-2012 RMKH2012 2.03±0.15 1.27±0.13 0.50±0.10 0.38±0.15 0.38±0.15 ZZR-Q/RU 21432.13-2012 RMKH3216 3.20±0.20 1.60±0.13 0.60±0.10 0.38±0.20 0.38±0.20 ZZR-Q/RU 21432.14-2012 RMKH3225 3.20±0.15 2.50±0.15 0.55±0.15 0.50±0.25 0.50±0.25 ZZR-Q/RU 21432.18-2012 RMKH5225/5025 2.50±0.15 0.55±0.15 0.60±0.25 0.60±0.25 ZZR-Q/RU 21432.15-2012 RMKH6332 3.20±0.15 0.55±0.15 0.60±0.25 0.60±0.25 ZZR-Q/RU 21432.16-2012
16	RMS automotive surge	Quality grade and generic specification: AEC-Q200. Detail specification: Q/RU 641-2025.
17	RMZ GJB sulfur-resistant zero-ohm	Quality grade: triangle J mark. Detail specifications: RMZ1005 to RMZ6332, GJB 6787/1 to 7-2011 respectively. Generic specification: GJB 6787-2009.
18	RMZ space-grade YC zero-ohm	Quality grade: YC. Detail specification: Q/QJA 20087/3-2019. Generic specification: GJB
19	RMHV high voltage	Quality grade: J. Detail specification: Q/RU 26077-2021. Generic specification: GJB

06 / SERIES TECHNICAL DATA

Selection checks and sources

Items to confirm before ordering

Interpret K, M, C, S, U, G, P and B within each family ordering guide. RMHT uses K for ±100 ppm/K in its test table but C in its ordering guide; confirm before ordering.

Confirm RMS2012 0.25/0.5 W, the automotive RMS 10 Ω boundary, the pulse RMS7142A 10 Ω boundary and the RMHV 100 MΩ boundary, which are listed as alternatives or overlap in the source.

Grade, military, space and automotive designations and standards are retained from the source. Verify applicable procurement specifications and supply documentation for the actual order.

Source datasheets and website traceability

This edition consolidates the 19 paired website datasheets retrieved on 2026-11-18. The reference numbers below are used throughout the book.

01 RM power thick film
https://inlanx.com/zh/products/rm-92100522

02 RM anti-sulfur thick film
https://inlanx.com/zh/products/rm-b145a98b

03 RM anti-sulfur zero-ohm
https://inlanx.com/zh/products/rm-aeccb56c

04 RM standard thick film
https://inlanx.com/zh/products/rm-9832d014

05 RM thin film
https://inlanx.com/zh/products/rm-b278ae07

06 RMHT high-temperature thick film
https://inlanx.com/zh/products/rmht

07 RMK GJB thick film
https://inlanx.com/zh/products/rmk-229733d9

08 RMK GJB thin film
https://inlanx.com/zh/products/rmk-2c36debc

09 RMS pulse / surge
https://inlanx.com/zh/products/rms

10 RM sulfur-resistant thick film
https://inlanx.com/zh/products/rm

11 RM1608 gold-electrode chip
https://inlanx.com/zh/products/rm1608

12 RMK space-grade YC thick film
https://inlanx.com/zh/products/rmk-yc

13 RMK YG-grade thick film
https://inlanx.com/zh/products/rmk-yg

14 RMK GJB sulfur-resistant thick film
https://inlanx.com/zh/products/rmk

15 RMKH precision / reliability
https://inlanx.com/zh/products/rmkh

16 RMS automotive surge
https://inlanx.com/zh/products/rms-rohs

17 RMZ GJB sulfur-resistant zero-ohm
https://inlanx.com/zh/products/rmz

18 RMZ space-grade YC zero-ohm
https://inlanx.com/zh/products/rmz-yc

19 RMHV high voltage
https://inlanx.com/zh/products/rmhv

07 / SERIES TECHNICAL DATA

Terminology and reading guide

This guide explains the symbols and source-specific designations used in the selection tables. Family reference numbers 01–19 identify the applicable product specification; a shared package code does not make two families interchangeable.

Term / symbol	Meaning in this datasheet
P / rated power	Continuous power rating under the temperature and mounting conditions stated for the family. Apply its derating curve. Pulse ratings apply only to the stated pulse duration.
Umax / limiting voltage	Upper voltage limit of the resistor element. This is a separate limit from rated power; both limits must be observed.
TCR / ppm/K	Temperature coefficient of resistance, in parts per million per kelvin. A temperature interval of 1 K equals 1 °C. A value of 100 ppm/K is 0.01% per kelvin.
R / ΔR / Rmax	R is resistance; ΔR is the change in resistance caused by a test. Rmax is the maximum resistance specified for a zero-ohm jumper. Preserve the distinction between R and ΔR in the acceptance criteria.
Numerical test limits	For a tabulated numerical limit a, a%R means (a/100) × R. For example, 0.5%R + 0.01 Ω means 0.005 × R + 0.01 Ω. Use +0.05 Ω for family 16 where stated; follow explicit full criteria in other rows.
K / M / Y / E / H and other codes	Source-specific characteristic or ordering codes. Their meanings depend on the family. Read them together with the corresponding ordering guide; the same letter is not a universal grade or TCR value.
GJB	Chinese military standard designation. The listed standard number identifies the source specification; it does not by itself establish certification or qualification of every supplied part.
YC / YG / space-grade	Quality-grade designations retained from the source datasheets. YC and YG are supplier-specific codes. Confirm the applicable procurement specification and order-specific supply documentation.
Anti-sulfur / sulfur-resistant	Separate family names retained from the sources: references 02/03 use anti-sulfur, while 10/14/17 use sulfur-resistant. Select by the family reference, suffix and test requirements, rather than these English labels alone.
Ref. / source	The two-digit reference links each row to one of the 19 source families. Source links are listed in section 06. Unresolved overlaps and inconsistent source codes remain identified there.